

电子灌封胶

● 双组份有机硅灌封胶 Two-component organosilicon potting compound

性能指标 Performance indicators	584T	584P	584Z	584H	584ZF
外观 A/B Appearance A/B	无色透明 Colourless and transparent	白色等/透明 White etc./Transparent	白色等/透明 White etc./Transparent	灰白色等/透明 Grey white, etc./Transparent	白色等/透明 White, etc./Transparent
密度 Density (g/mm ³ , A/B)	0.95~1.05	1.3/1.03	1.3/1.03	1.3/1.03	1.3/1.03
A 组分粘度 Component A Viscosity (pa.s)	1.5~2.5	5.5~11	7.5~13	7.5~13	7.5~13
B 组分粘度 Component B Viscosity (pa.s)	0.01~0.1	0.01~0.1	0.01~0.1	0.01~0.1	0.01~0.1
可操作时间 Operable time (min)	30~90	40~120	40~120	40~120	40~120
完全固化时间 Full curing time (h)	24	24	24	24	24
硬度 Hardness	10~30	20~40	20~50	20~50	20~50

(shore A)					
剪切强度 Shearing strength (MPa)	0.8	0.8	0.8	0.8	0.8
导热系数 Thermal conductivity (W/M·K)	0.3	0.3	0.7	2.0	0.7
阻燃等级 Flame retardant grade (UL94)	HB	HB	V0	HB	V0
防霉性 resistance to mould and mildew (级别 Grade)	/	/	/	/	0
介电强度 Dielectric strength (kv/mm)	≥18				
体积电阻 Volume resistance (Ω·cm, 25°C)	≥1.0×10 ¹⁴				
适用温度 Applicable temperature (°C)	-60~200				

584T 透明型灌封胶 584T Transparent Potting Compound

适用于电子元器件有透明要求的灌封、密封。

Suitable for potting and sealing of electronic components with transparent requirements.

584P 通用型灌封胶 584P general-purpose potting compound

适用于电子元器件的灌封、密封。

Suitable for potting and sealing of electronic components.

584Z 导热阻燃灌封胶 584Z Thermally Conductive Flame Retardant Potting Adhesive

适用于电子元器件有导热阻燃要求的各种灌封、密封。

Suitable for various potting and sealing of electronic components with thermal conductivity and flame retardant requirements.

584H 高导热型灌封胶 584H High Thermal Conductivity Potting Adhesive

适用于有高导热性要求的电子元器件灌封、密封。

Suitable for potting and sealing electronic components with high thermal conductivity requirements.

584ZF 导热阻燃防霉胶 584ZF Thermally Conductive Flame Retardant Mouldproof Adhesive

适用于有导热阻燃防霉要求的电子元器件灌封、密封。

Suitable for potting and sealing of electronic components with thermal conductivity, flame retardant and mould proof requirements.

特点用途 Features and Uses

584 有机硅灌封胶是一类双组分、室温固化、缩合脱醇型的有机硅灌封材料，自流平、耐高低温，具有优良的耐老化性、柔韧性、绝缘性，防潮、抗震。适用于电子元器件的各种浇注粘接、密封。完全符合欧盟 ROHS 指令要求。

584 organosilicon potting adhesive is a class of two-component, room temperature curing, condensation dehydrogenation type organosilicon potting material, self-leveling, high and low-temperature resistance, with excellent aging resistance, flexibility, insulation, moisture, and shock resistance. Suitable for a variety of electronic components cast bonding, and sealing. Fully compliant with the EU ROHS directive requirements.

操作工艺 Operation process

- 1、混合前，把 A、B 组分在各自的容器内充分搅拌、摇晃均匀。
 1. Before mixing, the A, B components in their respective containers fully stirred, shaking evenly.
- 2、按配比称取 A、B 组分，放入混合罐中，充分搅拌混合均匀。最好抽真空脱泡 10 分钟左右，配胶量不宜超过容器的 1/2，否则在脱泡时胶会溢出。
 2. Weigh A and B components according to the ratio, put them into the mixing tank and mix them well. It is best to vacuum defoaming for about 10 minutes, the amount of glue should not exceed 1/2 of the container, otherwise the glue will overflow when defoaming.
- 3、将混合好的胶料尽快灌注到需要灌封的产品中。
 3. Pour the mixed adhesive into the product that needs to be sealed as soon as possible.
- 4、灌封好的工件于室温下固化，表干后方可进入下道工序，完全固化需要 24 小时。
 4. The potting workpiece is cured at room temperature, the surface is dry before entering the next process, and it takes 24 hours for complete curing.

注意事项 Notes

- 1、A 组分若有沉淀或分层，应搅拌均匀后使用，不影响产品性能。
 1. If there is any precipitation or delamination of A component, it should be stirred well and used without affecting the performance of the product.
- 2、混合好的胶应一次用完，未用完的胶料和固化剂应密封保存。
 2. Mixed glue should be used up at one time, the unused glue and hardener should be sealed and stored.

- 3、密封贮存于阴凉干燥处，贮存期六个月。
3. Sealed storage in a cool and dry place for six months.
- 4、包装规格：11kg/套。
4. Packing specification: 11kg/set.

性能指标 Performance indicators	5850	585T	585D	585H
外观 Appearances A/B	无色透明 Colorless and transparent	无色透明 Colorless and transparent	白色/灰色 White/Grey	白色/灰色 White/Grey
密度 Density (g/mm ³ , A/B)	0.95~1.05	0.95~1.05	1.3~1.5	1.3~1.5
粘度 Viscosity (pa.s)	0.5~1.0	0.5~1.5	2.5~5.5	2.5~6.5
可操作时间 Operable time (min)	60~120	60~90	60~90	60~90
完全固化时间 Full curing time (h)	24	24	24	24
固化时间 Curing time (60°C, min)	40	40	40	40
硬度 Hardness (shore A)	/	30~65	30~65	30~65
剪切强度 Shearing strength (MPa)	/	0.8	0.8	0.8
导热系数 Thermal conductivity (W/M·K)	/	0.3	0.7	1.2
阻燃等级 Flame retardant grade (UL94)	/	HB	V0	HB
介电强度 Dielectric strength (kv/mm)	≥18			

体积电阻 Volume resistance ($\Omega \cdot \text{cm}$, 25°C)	$\geq 1.0 \times 10^{14}$
适用温度 Applicable temperature (°C)	-60~200

5850 硅凝胶 5850 Silicone Gel

俗称果冻胶，适用于各种电子元器件的密封保护，尤其精密电子元器件。

Commonly known as jelly glue, suitable for sealing protection of various electronic components, especially precision electronic components.

585T 透明型灌封胶 585T Transparent Potting Compound

适用于电子元器件有透明要求的灌封、密封。

Suitable for potting and sealing of electronic components with transparent requirements.

585D 导热阻燃灌封胶 585D Thermally Conductive Flame Retardant Potting Adhesive

适用于电子元器件有导热阻燃要求的各种灌封、密封。

Suitable for various potting and sealing of electronic components with thermal conductivity and flame retardant requirements.

585H 高导热型灌封胶 585H High Thermal Conductivity Potting Adhesive

适用于有高导热性要求的电子元器件灌封、密封。

Suitable for potting and sealing electronic components with high thermal conductivity requirements.

特点用途 Features and Uses

585 适用于大功率及散热要求高的电子元器件绝缘及防水。本品在固化反应中不产生任何副产物，可以应用于金属表面及 PC、PP、ABS、PVC 等材料。完全符合欧盟 ROHS 指令要求。

585 is suitable for insulation and waterproofing of electronic components with high power and high heat dissipation requirements. This product does not produce any by-products in the curing reaction, and can be applied to metal surfaces and materials such as PC, PP, ABS and PVC. It is fully compliant with the requirements of the EU ROHS Directive.

操作工艺 Operation process

- 1、混合前，首先把 A 组分和 B 组分在各自的容器内充分搅拌均匀。
 1. Before mixing, first of all, the A component and the B component in their respective containers to mix well.
- 2、按配比称取 A、B 组分，放入混合罐中，充分搅拌混合均匀。最好抽真空脱泡 10 分钟左右，配胶量不宜超过容器的 1/2，否则在脱泡时胶会溢出。
 2. Weigh A and B components according to the ratio, put them into the mixing tank and mix them well. It is best to vacuum defoaming for about 10 minutes, the amount of glue should not exceed 1/2 of the container, otherwise, the glue will overflow when defoaming.
- 3、将混合好的胶料尽快灌注到需要灌封的产品中。
 3. Pour the mixed adhesive into the product that needs to be sealed as soon as possible.

4、灌封工件可选择室温或者加热固化。60~80℃下 30 分钟即可固化。

4. Filling and sealing workpieces can choose room temperature or heat curing. 60~80℃ can be cured in 30 minutes.

注意事项 Notes

1、A、B 组分若有沉淀或分层，应搅拌均匀后使用，不影响产品性能。

1. If there is any precipitation or delamination of A and B components, they should be stirred evenly and used without affecting the product performance.

2、本品不能接触有机锡化合物、硫磺、硫化物、胺类化合物等产品，否则可能不固化。

2. This product can not contact with organic tin compounds, sulfur, sulfide, amine compounds and other products, otherwise it may not be cured.

3、密封贮存于阴凉干燥处，贮存期六个月。

3. Sealed storage in a cool dry place, storage period of six months.

4、包装规格：20KG/套。

4. Packaging specification: 20KG/set.

● 单组分有机硅灌封胶 Single-component silicone potting compound

性能指标 Performance indicators	592T	592B	592W	592
外观 Appearances	透明流体 Transparent Fluid	黑色流体 Black fluid	白色流体 White fluid	各色流体 By choice
密度 Densities (g/mm ³ ,)	1.0	1.1	1.1	1.0
粘度 Viscosity (pa.s)	6~10	8~15	8~15	6~10
表干时间 Surface drying time (min)	10~30	10~30	10~30	5~20
抗拉强度 Tensile strength (MPa)	0.8	1.0	1.0	0.7
延伸率 Elongation (%)	200~300	200~300	200~300	150~200
硬度 Hardness (shore A)	20~30	20~30	20~30	15~25
剪切强度 Shearing strength (MPa)	≥0.5	≥0.5	≥0.5	≥0.5
介电强度 Dielectric strength (kv/mm)	≥20	≥20	≥20	≥20
损耗因子 Loss factor (1.2MHz)	0.001	0.001	0.001	0.001
体积电阻 Volume resistance (Ω·cm, 25°C)	1.0×10 ¹⁵			
工作温度范围 Working	-60~250	-60~250	-60~250	-60~250

temperature range (°C)				
线收缩率 Wire shrinkage (%)	0.3	0.3	0.3	0.3

592T 硅橡胶密封剂 592T Silicone Rubber Sealant

脱肟型、透明，各种电子元器件的灌封。

Deoxime type, transparent, potting of various electronic components.

592B 硅橡胶密封剂 592B Silicone Rubber Sealant

脱肟型、黑色，发光二极管等电子元器件的灌封。

Deoxime type, black color, potting of electronic components such as light emitting diodes.

592W 硅橡胶密封剂 592W Silicone Rubber Sealant

脱肟型、白色，电器模块等电子元器件的灌封。

Deoxime type, white colour, potting of electronic components such as electrical modules.

582 硅橡胶密封剂 582 Silicone Rubber Sealant

脱醇型、透明，对聚碳酸酯(PC)、铜等材料不腐蚀，各种电子元器件的灌封。

Dehydrated, transparent, non-corrosive to polycarbonate (PC), copper and other materials, potting of various electronic components.

特点用途 Features and Uses

单组分有机硅灌封胶是室温固化的中性有机硅材料，低粘度，自流平，固化后为弹性体。耐高低温，具有优良的耐老化性、柔韧性、绝缘性，防潮、抗震、耐电晕、抗漏电。适用于小型或薄层(灌封厚度小于 7MM)的电子元器件、线路板、传感器、继电器等的灌封保护。

One-component silicone potting compound is room temperature curing neutral silicone material, low viscosity, self-leveling, cured elastomer. Resistant to high and low temperatures, with excellent aging resistance, flexibility, insulation, moisture, shock, corona resistance and resistance to leakage. Suitable for small or thin layers (potting thickness less than 7MM) of electronic components, circuit boards, sensors, relays and other potting protection.

操作工艺 Operation process

1、清洁表面：将被灌封物表面整理干净，除去锈迹、灰尘、水分及油污。

1. Clean the surface: the surface of the potting object will be clean, remove rust, dust, moisture and oil.

2、施胶：拧开胶管盖帽，刺开封口，将胶液挤到已清理干净的表面，使之自然流平。

2. Sizing: unscrew the hose cap, and prick open the sealing mouth, the glue will be squeezed to the surface has been cleaned up, so that the natural leveling.

3、固化：胶液吸收空气中的潮气，表面开始固化，逐渐向深层固化，在 24 小时(室温及 60%相对湿度)内固化深度为 3~4mm。

3. Curing: the glue absorbs moisture in the air, the surface begins to solidify, gradually to the deep curing, in 24 hours (room temperature and 60% relative humidity) within the curing depth of 3 ~ 4mm.

4、夏季温度高，湿度大，固化会快一些;冬季温度低，湿度小，固化会慢一些。

4. Summer temperature is high, high humidity, curing will be faster; winter temperature is low, low humidity, curing will be slower.

注意事项 Notes

硅橡胶吸潮固化，未用完的胶应密封保存。密封贮存于阴凉干燥处，贮存期9个月。

Silicone rubber absorbs moisture and cures, unused rubber should be sealed and stored. Sealed storage in a cool dry place, storage period of 9 months.

半流淌有机硅密封胶 Semi-Fluid Silicone Sealant				
性能指标 Performance indicators	591W	591B	591T	581
外观 Appearances	白色半流体 White semi-fluid	黑色半流体 Black semi-fluid	半透明半流体 Translucent semi-fluid	各色半流淌 By choice
密度 Densities (g/mm ³ ,)	1.15	1.15	1.02	1.15
表干时间 Surface drying time (min)	10~30	10~30	10~30	5~15
抗拉强度 Tensile strength (MPa)	1.0	1.0	1.0	1.0
延伸率 Elongation (%)	200~300	200~300	200~300	200~300
硬度 Hardness (shore A)	30~50	30~50	20~30	20~30
剪切强度 Shearing strength (MPa)	≥0.5	≥0.5	≥0.5	≥0.5
介电强度 Dielectric strength (kv/mm)	≥20	≥20	≥20	≥20
损耗因子 Loss factor (1.2MHz)	0.001	0.001	0.001	0.001
体积电阻 Volume resistance (Ω·cm, 25℃)	1.0×10 ¹⁵			
工作温度范围 Working temperature range (℃)	-60~250	-60~250	-60~250	-60~250

线收缩率 Wire shrinkage (%)	0.3	0.3	0.3	0.3
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591W 硅橡胶密封剂 591W Silicone Rubber Sealant

脱肟型、白色，电器模块等电子元器件的封装。

Deoxime type, white color, encapsulation of electronic components such as electrical modules.

591B 硅橡胶密封剂 591B Silicone Rubber Sealant

脱肟型、黑色，电子元器件、线路板、继电器、微波炉等的粘接密封。

Deoxime type, black colour, adhesive sealing for electronic components, circuit boards, relays, microwave ovens, etc.

591T 硅橡胶密封剂 591T Silicone Rubber Sealant

脱肟型、半透明，有透明要求的各类电子元器件的封装保护。

Deoxime type, semi-transparent, with transparent requirements of all kinds of electronic components encapsulation protection.

581 硅橡胶密封剂 581 Silicone Rubber Sealant

脱醇型、各色，对聚碳酸酯(PC)、铜等材料不腐蚀，用于各类电子元器件的封装保护。

Dehydrated, various colours, non-corrosive to polycarbonate (PC), copper and other materials, used for all kinds of electronic components encapsulation protection.

特点用途 Features and Uses

半流淌有机硅密封胶是一类单组分室温固化的中性有机硅材料，固化后为弹性体。具有优异的抗冷热交变性能、耐老化性、柔韧性、绝缘性，防潮、抗震、耐电晕、抗漏电。是传统 703、704 硅橡胶的换代产品。适用于电子线路板上部分电子元器件的局部封装保护。

Semi-flow silicone sealant is a class of one-component room temperature curing neutral silicone materials, cured elastomer. It has excellent resistance to hot and cold alternating properties, aging resistance, flexibility, insulation, moisture, shock, corona resistance, resistance to leakage, and is a replacement for the traditional 703, 704 silicone rubber, suitable for electronic circuit boards, part of the electronic components of the local encapsulation protection.

操作工艺 Operation process

清洁表面：将被密封物表面整理干净，除去锈迹、灰尘、水分及油污。

施胶：拧开胶管盖帽，刺开封口，将胶液挤到已清理干净的表面，使之自然流成半圆形。

固化：胶液吸收空气中的潮气，表面开始固化，逐渐向深层固化，在 24 小时(室温及 60% 相对湿度)内固化深度为 3~4mm。

夏季温度高，湿度大，固化会快一些；冬季温度低，湿度小，固化会慢一些。

Clean surface: Tidy up the surface of the sealed object and remove rust, dust, moisture and oil.

Sizing: Unscrew the cap of the hose, prick open the sealing mouth, squeeze the glue to the cleaned surface, and make it flow naturally into a semicircle.

Curing: the glue absorbs the moisture in the air, the surface begins to solidify, gradually to the deep curing, in 24 hours (room temperature and 60% relative humidity) within the curing depth of 3~4mm.

Summer temperature is high, high humidity, curing will be faster; winter temperature is low, low humidity, curing will be slower.

注意事项 Notes

- 1、硅橡胶吸潮固化，未用完的胶应密封保存。
1. Silicone rubber absorbs moisture and cures, unused rubber should be sealed and stored.
- 2、密封贮存于阴凉干燥处，贮存期 9 个月。
2. Sealed storage in a cool and dry place for 9 months.

不流淌有机硅密封胶 Non-flowing silicone sealant				
性能指标 Performance indicators	593	594	595	583
外观 Appearances	黑色 Black	透明 Transparent	白色 White	各色 By choice
密度 Densities (g/mm ³ ,)	1.1~1.4	0.9~1.1	1.1~1.4	1.1~1.4
表干时间 Surface drying time (min)	10~30	10~30	10~30	5~15
抗拉强度 Tensile strength (MPa)	1.0~2.0	1.0~2.0	1.0~2.0	1.0~2.0
延伸率 Elongation (%)	300~500	200~350	300~500	200~300
硬度 Hardness (shore A)	30~50	20~30	30~50	25~35
剪切强度 Shearing strength (MPa)	1.0~2.0	1.0~2.0	1.0~2.0	1.0~2.0
介电强度 Dielectric strength (kv/mm)	20	20	20	20
损耗因子 Loss factor (1.2MHz)	0.001	0.001	0.001	0.001
体积电阻 Volume resistance (Ω·cm, 25°C)	2.0×10 ¹⁴			
工作温度范围 Working	-60~250	-60~250	-60~250	-60~250

temperature range (°C)				
线收缩率 Wire shrinkage (%)	0.3	0.3	0.3	0.3
导热系数 Thermal conductivity (W/M·K)	0.3	0.3	0.3	0.3

593 硅橡胶密封剂 593 Silicone Rubber Sealant

脱肟型、黑色，适用于各类电子元器件的密封粘接。

Deoxime type, black color, suitable for sealing and bonding of all kinds of electronic components.

594 硅橡胶密封剂 594 Silicone Rubber Sealant

脱肟型、透明，适用于有透明要求的线路板等的防潮粘接密封。

Deoxime type, transparent, suitable for moisture-proof adhesive sealing of circuit boards etc. with transparent requirements.

595 硅橡胶密封剂 595 Silicone Rubber Sealant

脱肟型、白色，适用于冰箱、太阳能组件、电子元器件等的防潮粘接密封。

Deoxime type, white color, suitable for moisture-proof adhesive sealing of refrigerators, solar modules, electronic components and so on.

583 硅橡胶密封剂 583 Silicone Rubber Sealant

脱醇型、各色，对聚碳酸酯(PC)、铜等材料不腐蚀，适用于各类电子元器件的密封粘接。

Dehydrated, various colors, non-corrosive to polycarbonate (PC), copper and other materials, suitable for all kinds of electronic components sealing bonding.

特点用途 Features and Uses

不流淌有机硅密封胶是一类单组分室温固化的中性有机硅材料，耐高低温，具有优良的耐老化性、柔韧性、绝缘性，防潮、抗震、耐电晕、抗漏电。立面不流淌、可粘接钢铁、玻璃、PVC、ABS等材料。适用于电子元器件等的各类粘接密封。

Non-flow silicone sealant is a class of one-component room temperature curing neutral silicone materials with high and low temperature resistance, excellent aging resistance, flexibility, insulation, moisture, shock, corona resistance, and resistance to leakage. The surface does not flow, can be bonded to steel, glass, PVC, ABS and other materials. Suitable for electronic components and other types of adhesive sealing.

操作工艺 Operation process

- 1、清洁表面：将被粘物表面整理干净，除去锈迹、灰尘、水分及油污。
1. Clean the surface: The surface of the object to be adhered to clean, remove rust, dust, moisture and oil.
- 2、施胶：切开胶嘴，放入胶枪中，将胶液挤到已清理干净的表面，使之分布均匀。
2. Glue application: Cut the glue nozzle, put it into the glue gun, and squeeze the glue into the surface that has been cleaned up, so it is evenly distributed.
- 3、粘接密封：施胶后 20 分钟内必须进行粘接，将被粘面合拢固定即可。
3. Adhesive sealing: 20 minutes after the glue application must be bonded, the adhesive surface will be fixed together.
- 4、固化：室温固化 24 小时达到最高强度。

夏季温度高，固化会快一些；冬季温度低，固化会慢一些。

4. Curing: room temperature curing for 24 hours to reach the highest strength.

Higher temperature in summer, curing will be faster; lower temperature in winter, curing will be slower.

注意事项 Notes

硅橡胶吸潮固化，未用完的胶应密封保存。密封贮存于阴凉干燥处，贮存期 9 个月。

Silicone rubber absorbs moisture and cures, unused rubber should be sealed and stored. Sealed storage in a cool dry place, storage period of 9 months.

有机硅导热胶 Silicone thermal conductive adhesive			
性能指标 Performance indicators	595D	595HD	595H
外观 Appearances	白色 White	白色 White	白色 White
密度 Density (g/mm ³ ,)	1.3~1.7	1.3~1.7	1.3~1.7
表干时间 Surface drying time (min)	20~40	20~40	20~40
抗拉强度 Tensile strength (MPa)	0.7~1.5	0.7~1.5	0.7~1.5
延伸率 Elongation (%)	200~300	200~300	200~300
硬度 Hardness (shore A)	30~50	30~50	30~50
剪切强度 Shearing strength (MPa)	0.7~1.5	0.7~1.5	0.7~1.5
介电强度 Dielectric strength (kv/mm)	20	20	20
损耗因子 Loss factor (1.2MHz)	0.001	0.001	0.001
体积电阻 Volume resistance (Ω·cm, 25°C)	2.0×10 ¹⁴		

工作温度范围 Working temperature range (°C)	-60~280	-60~280	-60~280
线收缩率 Wire shrinkage (%)	0.5	0.5	0.5
导热系数 Thermal conductivity (W/M·K)	0.8	1.2	2.0

595D 导热型硅橡胶 595D Thermally Conductive Silicone Rubber

代替导热硅脂，用于 CPU 与散热器等的填充粘接。

Replaces thermally conductive silicone grease and fills and bonds CPUs to heat sinks, etc.

595HD 导热型硅橡胶 595HD Thermally Conductive Silicone Rubber

用于要求较高导热性的晶闸管智能模块与散热器的填充粘接。

For filler bonding of thyristor smart modules and heat sinks that require high thermal conductivity.

595H 导热型硅橡胶 595H Thermally Conductive Silicone Rubber

用于大功率电器模块与散热器之间的填充粘接。

For filler bonding between high-power electrical modules and heat sinks.

特点用途 Features and Uses

单组分室温固化的中性有机硅材料，耐高低温，具有优良的耐老化性、柔韧性、绝缘性，防潮、抗震、耐电晕、抗漏电。立面不流淌、可粘接钢铁、玻璃、PVC、ABS 等材料。适用于电子元器件的导热粘接密封。

Single-component room temperature curing neutral organosilicon material, high and low-temperature resistance, excellent aging resistance, flexibility, insulation, moisture-proof, shock resistance, corona resistance, and resistance to leakage. The surface does not flow and can be bonded to steel, glass, PVC, ABS, and other materials. Suitable for electronic components of the thermal conductivity adhesive sealing.

操作工艺 Operation process

- 1、清洁表面：将被粘物表面整理干净，除去锈迹、灰尘、水分及油污；
1. Clean the surface: Tidy up the surface of the object to be adhered to, remove rust, dust, moisture and oil;
- 2、施胶：刺开铝封口，将胶液挤到已清理干净的表面，使之分布均匀；
2. Sizing: Prick open the aluminum seal, squeeze the glue to the surface that has been cleaned up, so that it is evenly distributed;
- 3、粘接密封：施胶后 20 分钟内必须进行粘接，将被粘面合拢固定即可；
3. Adhesive sealing: 20 minutes after the application of adhesive must be bonded, the adhesive surface can be fixed together;
- 4、固化：室温固化 24 小时达到最高强度。
夏季温度高，固化会快一些；冬季温度低，固化会慢一些。
4 Curing: Room temperature curing for 24 hours to reach the highest strength.

Summer temperature is high, curing will be faster; winter temperature is low, curing will be slower.

注意事项 caveat

- 1、硅橡胶吸潮固化，未用完的胶应密封保存。
1. Silicone rubber absorbs moisture and cures, unused rubber should be sealed and stored.
- 2、密封贮存于阴凉干燥处，贮存期 9 个月。
2. Sealed storage in a cool and dry place for 9 months.

庆隆达（山西）科技新材料

● 低粘度三防漆 Low-viscosity triple-proof paint

性能指标 Performance indicators	5901	590K	590P
外观 Appearances	透明 Transparent	透明 Transparent	透明 Transparent
主要成分 Main components	脱脲硅胶 Deoxidised silica gel	改性丙烯酸 Modified acrylic acid	改性聚氨酯 Modified polyurethane
固含量 Solid content (%)	100	> 35	100
密度 Densities (g/mm ³ ,)	1.0±0.1	1.0±0.1	1.0±0.1
表干时间 Surface drying time (min)	10~30	3~10	3~10
全固时间 Full solidification time	25°C24h	80°C3 分钟	80°C3 分钟
抗拉强度 Tensile strength (MPa)	1.0	4.5	4.5
扯断伸长率 Tearing elongation (%)	100	30	100
硬度 Hardness (shore A)	20	65	65
剪切强度 Shearing strength (MPa)	1.0	2.5	2.5
剥离强度 Peeling strength (N/mm)	> 6	> 6	> 6
介电强度 Dielectric strength (kv/mm)	25	50	50
介电常数 Dielectric constant (1.2MHz)	3.0	2.7	2.7
损耗因子 Loss factor (1.2MHz)	0.005	0.002	0.002

体积电阻 Volume resistance ($\Omega \cdot \text{cm}$, 25°C)	2.0×10^{14}	1.0×10^{14}	1.0×10^{14}
工作温度范围 Working temperature range (°C)	-50~250	-50~150	-50~150

5901 有机硅三防漆 5901 Organic Silicon Triple Anti Varnish

脱脞硅胶，用于 LED 电子元器件涂覆保护，不适宜铜、PC 材料。

Deoxidising silica gel, used for coating protection of LED electronic components, is not suitable for copper and PC materials.

590K 丙烯酸三防漆 590K Acrylic Triple Defence Paint

改性丙烯酸，不含硅、酮、酚等材料，UV 光下蓝色，便于检测。

Modified acrylic, free of silicone, ketone, phenol and other materials, blue colour under UV light, easy to detect.

590P 聚氨酯三防漆 590P polyurethane triple-proof paint

改性聚氨酯，不含硅、酮、酚等材料，UV 光下蓝色，便于检测。

Modified polyurethane, free of silicone, ketone and phenol, blue colour under UV light, easy to detect.

特点用途 Features and Uses

本品为低粘度中性高分子复合材料，单组分，易于喷涂、浸涂及刷涂。具有良好的耐高低温性能；其固化后成一层透明保护膜，具有优越的绝缘、防潮、防漏电、防震、防尘、防腐蚀、防老化、耐电晕等性能。广泛应用于电子元器件的表面披覆保护。

This product is a low viscosity neutral polymer composite material, single-component, easy to spray, dip coating and brush coating. It has good resistance to high and low temperatures; after curing into a transparent protective film, it has superior insulation, moisture-proof, leakage-proof, shock-proof, dust-proof, corrosion-proof, anti-aging, corona-resistant and other properties. Widely used in electronic components surface coating protection.

操作工艺 Operation process

1. 将胶液装入浸桶中，进行浸涂，线路板或元器件浸入速度不宜太快，以免产生气泡。
1. Load the glue into the dipping bucket for dip coating, the circuit board or components should not be immersed too fast to avoid air bubbles.
2. 喷涂时，将胶液装入喷壶中，进行喷涂。喷涂结束后使用稀释剂清洗喷壶。
2. When spraying, fill the spray bottle with adhesive solution and spray. Use thinner to clean the spray bottle after spraying.
3. 若胶液粘度稠，可用稀释剂稀释。稀释剂的加入量大，胶的粘度低，涂胶的厚度薄；反之，胶的粘度高，涂胶的厚度厚。稀释剂的加入量建议为 20~40%。
3. If the viscosity of the glue is thick, diluent can be used to dilute. When a large amount of glue viscosity is low, the thickness of the coating is thin; on the contrary, the viscosity of the glue is high, the thickness of the coating thick. The amount of thinner is recommended to be 20~40%.

注意事项 Notes

- 1、未用完的胶液应密封保存。再次使用时，若封口处或者表面有结皮，将其去除即可，不影响正常使用。
 1. Unused glue should be sealed and stored. When used again, if there is crust on the seal or surface, remove it, which will not affect the normal use.
- 2、施工现场应有良好的通风设施。
 2. The construction site should be well-ventilated.
- 3、阴凉干燥处密封贮存，贮存期 6 个月。过期后经检验合格仍可使用。
 3. Cool and dry place sealed storage for 6 months. After the expiry of the test, it can still be used.

庆隆达（山西）科技新材料

● 双组份环氧灌封胶 (Two-component encapsulating system based on epoxy resin.)

性能指标 (Performance)		484T	484P	484L	484D	484HTR
固化前 (Before curing)	外观颜色 (Color)	透明液体 (Clear liquids)	黑色/褐色 (Black / Brown)	黑色/褐色 (Black / Brown)	黑色/褐色 (Black / Brown)	黑色/透明 (Black / Clear liquids)
	粘度 (Pa.S, A/B) (Viscosity)	4/0.7	18/0.1	12/0.1	18/0.1	45/0.1
	密度 (g/cm ³ , A/B) (Density)	1.1/1.0	1.6/1.1	1.5/1.1	1.8/1.1	1.8/1.1
重量配比 (A : B) (Mixing ratio, weight-%)		2 : 1	5 : 1	5 : 1	5 : 1	5 : 1
可操作时间 (min) (Pot life)		30	60	60	60	60
完全固化时间 (h) (Complete chemical curing)		48	48	48	48	48
固化后 (After curing)	邵氏硬度 (S.D) (Shore-D-hardness)	≥80	≥80	≥80	≥80	≥80
	线收缩率 (%) (Curing shrinkage)	0.8	0.5	0.5	0.5	0.5
	导热系数 (W/M·K) (Thermal conductivity)	0.3	0.3	0.3	0.7	0.7
	阻燃等级 (UL94) (Burning behaviour)	HB	V0	HB	V0	V0
	介电强度 (kv/mm) (Dielectric strength)	≥25				
	体积电阻 (Ω·cm) (Volume resistance)	1.2×10 ¹⁴				
	使用温度范围 (°C) (Temperature)	-40~90				-40~150

	range of use)		
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484T 透明型灌封胶

适用于数码管的常温灌封

484P 通用型灌封胶

用于一般电子元器件灌封和线路板封闭保护

484L 低粘度灌封胶

适用于对流动性要求高的线路板的灌封

484D 导热阻燃灌封胶

适用于对散热及阻燃要求较高的模块和线路板的灌封保护

484HTR 耐高温灌封胶

适用于耐高温工况的零部件粘接、密封、灌封

特点用途:

484 环氧灌封是一类双组份、自流平、室温固化的环氧树脂灌封材料, 具有优良的耐老化性、防潮性、电气绝缘性, 高硬度和高击穿电压。适用于电子元器件的各种浇注粘接、密封。

操作工艺:

- 1、将被灌封处清理干净, 无油、无水、无杂物。
- 2、将 A 组分搅拌均匀, 按配比称取 A 组分和 B 组分, 放入混合罐中, 充分搅拌混合均匀, 最好抽真空脱泡 10 分钟左右, 配胶量不宜超过容器的 1/2, 否则在脱泡时胶会溢出。
- 3、将混合好的胶料尽快灌注到需要灌封的产品中。
- 4、灌封好的工件于室温下固化, 完全固化需要 1~2 天。夏季温度高, 固化会快一些; 冬季温度低, 固化会慢一些, 在 60°C 保温 2~3 小时即可装配。

注意事项:

- 1、A 组分若有沉淀或分层, 应搅拌均匀后使用, 不影响产品性能。
- 2、混合好的胶应一次用完, 未用完的胶料和固化剂应密封保存。
- 3、密封贮存于阴凉干燥处, 贮存期六个月。
- 4、包装规格: 484T 为 30kg/套, 其他为 12kg/套。

484T transparent potting compound

It is suitable for room temperature potting of digital tubes

484P General Purpose Encapsulant

It is used for potting of general electronic components and circuit board closure protection

484L low viscosity encapsulant

It is suitable for potting circuit boards with high flow requirements

484D thermally conductive flame retardant potting compound

It is suitable for potting protection of modules and circuit boards with high requirements for heat dissipation and flame retardancy

484HTR High Temperature Resistant Encapsulant

It is suitable for bonding, sealing and potting parts under high temperature conditions

Attributes and Application

484 epoxy potting is a class of two-component, self-leveling, room temperature curing epoxy resin potting material, with excellent aging resistance, moisture resistance, electrical insulation,

high hardness and high breakdown voltage. It is suitable for all kinds of pouring bonding and sealing of electronic components.

Processing

1. Clean up the potting place, no oil, no water, no debris.
2. Stir the A component evenly, weigh the A component and the B component according to the ratio, put it into the mixing tank, fully stir and mix evenly, it is best to vacuum and deaeration for about 10 minutes, and the amount of glue should not exceed 1/2 of the container, otherwise the glue will overflow during degassing.
3. Pour the mixed rubber into the product that needs to be potted as soon as possible.
4. The potted workpiece is cured at room temperature, and it takes 1~2 days to completely cure. In summer, the temperature is high, and the curing will be faster; The temperature is low in winter, the curing will be slower, and it can be assembled after 2~3 hours at 60°C.

Notes:

1. If there is precipitation or stratification of component A, it should be stirred evenly and used without affecting the performance of the product.
2. The mixed glue should be used up at one time, and the unused rubber and curing agent should be sealed and stored.
3. Sealed and stored in a cool and dry place for six months.
4. Packing specifications: 30kg/set for 484T, 12kg/set for others.

性能指标		485T	485B
固化前	外观颜色	透明	灰黑色
	粘度 (Pa.S, A/B)	15~50	25~60
	密度 (g/cm ³ , A/B)	1.05±0.2	1.5±0.2
体积配比 (A : B)		1 : 1	1 : 1
可操作时间 (min, 23°C)		5	5
初固时间 (min, 23°C)		10~15	10~15
固化后	邵氏硬度 (S.D)	75~85	75~85
	剪切强度 (MPa)	15~25	15~25
	延伸率 (%)	5~20	5~20
	阻燃等级 (UL94)	V0	V0
	使用温度范围 (°C)	-50~120	-50~120

485T 增韧快固环氧胶

透明，用于金属、陶瓷、塑料、玻璃、纤维制品、工艺品、宝石等的快速粘接固定。

485B 增韧快固环氧胶

灰黑色，用于新能源电池、变压器、线圈、磁芯等电子元器件的粘接、密封、灌封。

特点用途

增韧快固环氧胶为双组份 1 : 1 (体积比) 配比、10 分钟快速固化胶，凝胶无烟化、柔韧，具有优良的耐老化性能、防潮性、电气绝缘性，弹性抗震和高击穿电压。适用于电子元器件的各种浇注 4 粘接、密封、灌封。

操作工艺

前期准备：保证灌封表面无油污、无灰尘。长期存放由于比重大容易分层，用前应搅拌均匀后使用，不影响产品性能。

混合胶液：将固化剂 B 按比例加入胶料里，边搅拌边加入，注意要刮壁，搅拌均匀、颜色一致为好。混合好的胶液应在 5 分钟内用完。可采用自动混料灌装机。

注意事项

- 1、若有沉淀或分层，应搅拌均匀后使用，不影响产品性能。
- 2、混合好的胶应一次用完，未用完的胶料和固化剂应密封保存。
- 3、密封贮存于阴凉干燥处，贮存期六个月。
- 4、包装规格/400mL/组，20kg/套。

485T toughened fast-curing epoxy adhesive

Transparent, used for rapid bonding and fixing of metals, ceramics, plastics, glass, fiber products, handicrafts, gemstones, etc.

485B toughened fast-curing epoxy adhesive

Gray and black, used for bonding, sealing and potting of electronic components such as new energy batteries, transformers, coils, and magnetic cores.

Attributes and Application

Toughened fast-curing epoxy adhesive is a two-component 1:1 (volume ratio) ratio, 10 minutes fast-curing adhesive, the gel is smoke-free, flexible, and has excellent aging resistance, moisture resistance, electrical insulation, elastic shock resistance and high breakdown voltage. It is suitable for all kinds of pouring bonding, sealing and potting of electronic components.

Processing

Preliminary preparation: ensure that the potting surface is free of oil and dust. Long-term storage is easy to stratify due to the specific gravity, so it should be stirred evenly before use, and the product performance will not be affected.

Mixed glue: add curing agent B to the rubber compound in proportion, add it while stirring, pay attention to scraping the wall, stir evenly and the color is consistent. The mixed glue should be used up within 5 minutes. Automatic mixing filling machine can be used.

Notes:

1. If there is precipitation or delamination, it should be stirred evenly and used without affecting the performance of the product.
2. The mixed glue should be used up at one time, and the unused rubber and curing agent should be sealed and stored.
3. Sealed and stored in a cool and dry place for six months.
4. Packing specification/400mL/group, 20kg/set.

● 单组分环氧胶 (One-component encapsulating system based on epoxy resin.)

性能指标	5521	5522	5523	5524	5526
外观	白色或黑色	无色	白色或黑色	黑色	白色或黑色
粘度 (mpa.s, 25°C)	3000	5000	10000~20000	20000	30000~40000
密度 (g/cm ³)	1.2	1.2	1.3	1.3	1.4
固化条件	120°C30 分钟	100°C60 分钟	100°C90 分钟	80°C90 分钟	120°C30 分钟
剪切强度 (钢/钢, Mpa)	13	13	15	13	15
体积电阻率 (Ω·cm, 25°C)	1.3×10 ¹⁵	1.3×10 ¹⁵	1.5×10 ¹⁵	1.3×10 ¹⁵	1.5×10 ¹⁵
表面电阻率 (Ω, 25°C)	1.2×10 ¹⁵	1.2×10 ¹⁵	1.3×10 ¹⁵	1.2×10 ¹⁵	1.3×10 ¹⁵
介电强度 (kv/mm)	20~22	20~22	20~22	20~22	20~22
抗张强度 (kg/mm ²)	11	11	13	11	13
抗压强度 (kg/mm ²)	13	13	15	13	15
收缩率 (%)	< 0.5	< 0.5	< 0.5	< 0.5	< 0.5
玻璃化转变温度 (°C)	140	140	150	140	150

5521 单组分环氧灌封胶

表面光泽可为亮光或者哑光, 颜色可为白色或者黑色, 粘度低, 适用于较小狭缝的灌封, 120°C 条件下 30 分钟固化。

5522 单组分环氧灌封胶

无色透明、表面效果好, 100°C60 分钟固化。

5523 单组分环氧灌封胶

表面光泽可为亮光或者哑光, 颜色可为白色或者黑色, 流平效果好, 适用于手工点胶或机器自动点胶, 100°C 条件下 90 分钟固化。

5524 单组分环氧灌封胶

黑色自流平, 80°C90 分钟固化, 属于低温固化型。

5526 单组分环氧灌封胶

表面光泽可为亮光或者哑光, 颜色可为白色或者黑色, 流平效果好, 适用于手工点胶或机器自动点胶, 120°C 条件下 90 分钟固化。

特点用途

此系列单组分环氧灌封胶为加热固化单组分环氧灌封胶。具有储存稳定, 粘接强度高, 绝缘

性能良好, 较双组份使用方便, 适用性强等特点。适用于继电器、电容器、触发器、IC 电路以及计算机、电视机、冰箱、汽车、摩托车等各类电子元器件的灌封。

使用方法

- 1、将胶从冰箱拿出, 放在室温与外界平衡 1~2 小时。
- 2、将胶液手工或机器灌入需封装的元器件内或表面。
- 3、缓慢升温加热固化, 有利于气泡逸出和胶液渗透填充缝隙, 确保各项性能优良。
- 4、用毕, 应及时盖好盖, 并放入冰箱 5°C 下保存。

注意事项

- 1、本品于 5°C 下贮存有效期为 3 个月, 超过贮存期若粘度合适仍可使用。
- 2、应根据实际固化条件, 被加工元件的特性进行固化试验, 以确保适合于特定产品的最佳固化条件。
- 3、本品为非危险品, 按非危险品储存及运输。
- 4、包装规格: 1kg。

5521 one-component epoxy encapsulant

The surface gloss can be bright or matte, the color can be white or black, the viscosity is low, it is suitable for potting small slits, and it cures in 30 minutes at 120°C.

5522 one-component epoxy encapsulant

Colorless and transparent, good surface effect, curing at 100°C for 60 minutes.

5523 one-component epoxy encapsulant

The surface gloss can be bright or matte, the color can be white or black, the leveling effect is good, suitable for manual dispensing or machine automatic dispensing, and 90 minutes curing at 100°C.

5524 one-component epoxy encapsulant

Black self-leveling, 80°C 90 minutes curing, low temperature curing type.

5526 one-component epoxy encapsulant

The surface gloss can be bright or matte, the color can be white or black, the leveling effect is good, suitable for manual dispensing or machine automatic dispensing, and 90 minutes curing at 120°C.

Attributes and Application

This series of one-component epoxy encapsulants is a heat-curing one-component epoxy encapsulant. It has the characteristics of stable storage, high bonding strength, good insulation performance, easy to use and strong applicability compared with two-component. It is suitable for potting relays, capacitors, flip-flops, IC circuits, computers, televisions, refrigerators, automobiles, motorcycles and other electronic components.

Processing

1. Take the glue out of the refrigerator and put it at room temperature to balance with the outside world for 1~2 hours.
2. Pour the glue into the components to be encapsulated or on the surface by hand or machine.
3. Slow heating and curing, which is conducive to the escape of bubbles and the penetration

of glue to fill the gaps, to ensure excellent performance.

4. After use, the lid should be covered in time and stored in the refrigerator at 5°C.

Notes:

1. The validity period of this product is 3 months when stored at 5°C, and it can still be used if the viscosity is suitable after the storage period.

2. The curing test should be carried out according to the actual curing conditions and the characteristics of the processed components to ensure the best curing conditions suitable for specific products.

3. This product is non-dangerous goods, and it is stored and transported as non-dangerous goods.

4. Packing: 1kg.

性能参数	5515	5516
外观	黑色/白色粘稠物	黑色粘稠物
粘度 (pa.s, 25°C)	80	100~150
密度 (g/cm ³)	1.5	1.5
固化条件	120°C 30 分钟	120°C 30 分钟
剪切强度 (钢/钢, Mpa)	18	18
体积电阻率 (Ω·cm, 25°C)	1.4×10^{15}	1.4×10^{15}
介电强度 (kv/mm)	> 20	> 20
介电常数 (1MHz, 25°C)	4	4
线膨胀系数 (cm/°C)	$< 5 \times 10^{-15}$	$< 5 \times 10^{-15}$
硬度 (shore D)	83~85	83~85
收缩率 (%)	< 0.15	< 0.15
玻璃化转变温度 (°C)	150	150

5515 单组分环氧包覆胶

5515 单组分环氧包覆胶为加温固化单组分环氧胶黏剂，亮光，主要用于金属、线圈等器件的包裹、密封。

5516 单组分环氧邦定胶

5516 单组分环氧邦定胶为加温固化单组分环氧胶黏剂，亮光，主要用于 IC 芯片、线路板等电子元器件的邦定、密封。。

特点用途

此系列单组分环氧包覆胶为加热固化单组分环氧灌封胶。具有储存稳定，粘度适中，绝缘性能良好，粘接性能高，较双组份使用方便等特点。适用于金属、线圈以及电机等元件的邦定、密封。

使用方法

- 1、将胶从冰箱拿出，放在室温与外界平衡 1~2 小时。
- 2、将胶点在基板上，若胶的粘度较高，可先将胶预热 40~50°C 后涂胶，也可不预热使用。
- 3、升温加热固化。
- 4、用毕，应及时盖好盖，并放入冰箱 5°C 下保存。

注意事项

- 1、本品于 5°C 下贮存有效期为 3 个月，超过贮存期若粘度合适仍可使用。
- 2、应根据实际固化条件，被加工元件的特性进行固化试验，以确保适合于特定产品的最佳固化条件。
- 3、本品为非危险品，按非危险品储存及运输。
- 4、包装规格：1kg。

5515 one-component epoxy coating adhesive

5515 one-component epoxy coating adhesive is a heating and curing one-component epoxy adhesive, which is mainly used for wrapping and sealing metals, coils and other devices.

5516 one-component epoxy bonding rubber

5516 one-component epoxy bonding adhesive is a heating and curing one-component epoxy adhesive, which is mainly used for the bonding and sealing of IC chips, circuit bench electronic components.

Attributes and Application

This series of one-component epoxy encapsulating adhesives is a heat-curing one-component epoxy encapsulant. It has the characteristics of stable storage, moderate viscosity, good insulation performance, high bonding performance, and easy to use compared with two-component. It is suitable for bonding and sealing of metals, coils, motors and other components.

Processing

1. Take the glue out of the refrigerator and put it at room temperature to balance with the outside world for 1~2 hours.
2. Glue dotted on the substrate, if the viscosity of the glue is high, the glue can be preheated at 40~50 °C before gluing, or it can be used without preheating.
3. Heating and curing.
4. After use, the lid should be covered in time and stored in the refrigerator at 5°C.

Notes:

1. The validity period of this product is 3 months when stored at 5°C, and it can still be used if the viscosity is suitable after the storage period.
2. The curing test should be carried out according to the actual curing conditions and the characteristics of the processed components to ensure the best curing conditions suitable for specific products.
3. This product is non-dangerous goods, and it is stored and transported as non-dangerous goods.
4. Packing: 1kg.

性能参数	5531	5532
外观	白色触变膏状	黑色触变膏状
粘度 (pa.s, 25°C)	80~150	80~150
固化条件	120°C 30 分钟	120°C 30 分钟
剪切强度 (钢/钢, Mpa)	21	21

体积电阻率 ($\Omega\cdot\text{cm}$, 25°C)	1.5×10^{15}	1.5×10^{15}
表面电阻率 (Ω , 25°C)	1.2×10^{15}	1.2×10^{15}
抗张强度 (kg/mm^2)	13	13
抗压强度 (kg/mm^2)	15	15
硬度 (shore D)	83	83
收缩率 (%)	< 0.5	< 0.5
热变形温度 (°C)	> 150	> 150

5531 单组分环氧结构胶

白色触变性膏状

5532 单组分环氧结构胶

黑色触变性膏状

特点用途

单组分环氧结构胶为中高温固化单组分环氧胶。具有储存稳定，粘接强度高，绝缘性能良好，较双组份使用方便，固化时具有触变性，适用性强等特点，固化物可以是黑色或白色固体。适用于金属、塑料、玻璃等材质的粘接。

使用方法

- 1、将胶从冰箱拿出，放在室温与外界平衡 1~2 小时。
- 2、将胶涂布于需粘接的器件上两面贴合。
- 3、升温加热固化。
- 4、用毕，应及时盖好盖，并放入冰箱 5°C 下保存。

注意事项

- 1、本品于 5°C 下贮存有效期为 3 个月，超过贮存期若粘度合适仍可使用。
- 2、应根据实际固化条件，被加工元件的特性进行固化试验，以确保适合于特定产品的最佳固化条件。
- 3、本品为非危险品，按非危险品储存及运输。
- 4、包装规格：300mL/筒，25 筒/箱。

5531 one-component epoxy structural adhesive

White thixotropic paste

5532 one-component epoxy structural adhesive

Black thixotropic paste

Attributes and Application

One-component epoxy structural adhesive is a medium-high temperature curing one-component epoxy adhesive. It has the characteristics of stable storage, high bonding strength, good insulation performance, easier to use than two-component, thixotropic and strong applicability when curing, and the cured object can be black or white solid. It is suitable for bonding metal, plastic, glass and other materials.

Processing

1. Take the glue out of the refrigerator and put it at room temperature to balance with the

outside world for 1~2 hours.

2. Spread the adhesive on both sides of the device to be bonded.

3. Heating and curing.

4. After use, the lid should be covered in time and stored in the refrigerator at 5°C.

Notes:

1. The validity period of this product is 3 months when stored at 5°C, and it can still be used if the viscosity is suitable after the storage period.

2. The curing test should be carried out according to the actual curing conditions and the characteristics of the processed components to ensure the best curing conditions suitable for specific products.

3. This product is non-dangerous goods, and it is stored and transported as non-dangerous goods.

4. Packing specification: 300mL/tube, 25 tubes/carton.

庆隆达（山西）科技新材料有限公司

● 双组份聚氨酯灌封胶 (Two-component encapsulating system based on polyurethane.)

性能指标	981	982	983	984	985
外观	白色/黄色	白色/黄色	白色/黄色	白色/黄色	白色/黄色
粘度 (mpa.s, A/B)	5000~8000/300~380				半流淌
混合后粘度 (mpa.s)	3000~5000				半流淌
可操作时间 (min)	≤30	30~45	45~60	45~60	30~60
初步固化时间 (h)	3~5	5~7	8~10	8~10	3~6
完全固化时间 (h)	24	36	48	48	24
硬度 (shore A/D)	≥80D	80±10A	60±10A	40±10A	80±10A
线收缩率 (%)	0.3				
比重 (g/mm ³)	1.5~1.7				
工作温度范围 (°C)	-60~150				
介电强度 (kv/mm)	≥25				
体积电阻率 (Ω·cm, 25°C)	1.0×10 ¹⁵				
导热系数 (W/M·K)	≥0.6				
剪切强度 (MPa)	≥3.5	≥2.3	≥1.5	≥0.8	≥4.5

981 聚氨酯灌封胶

用于各种电子元器件如精密电容器等的灌封。固化后高硬度，是替代环氧树脂的好材料。需具备真空脱泡和加温设备。

982 聚氨酯灌封胶

用于精密避雷器、各种变压器、互感器、滤波器、控制板、点火器等的灌封粘接。

983 聚氨酯灌封胶

通用型，适用于各类电子产品的灌封。

984 聚氨酯灌封胶

有优异的弹性和韧性，可返修，电性能优秀，可替代有机硅灌封胶。

985 聚氨酯粘接胶：

半流淌，用于电子元器件的粘接密封。

特点用途

双组份、室温固化、硬度可调的聚氨酯材料，流动性好，常温固化，固化后成弹性橡胶体。具有极佳的耐高低温、耐水解稳定性和优异的绝缘性能。对灌封后的电器零件具有固定、绝缘、散热、防爆、保密等多种功能。适用于高压、高频、湿热环境及水下仪器、仪表等电子元器件的各种浇注粘接、密封。

操作工艺

- 1、将被灌封处清理干净，无油、无水、无杂物。
- 2、按配比称取 A、B 组分，放入混合罐中，充分搅拌混合均匀（搅拌时不要把空气搅入胶中）。最好抽真空脱泡 5 分钟左右，配胶量不宜超过容器的 1/2，否则在脱泡时胶会溢出。
- 3、将混合好的胶料缓慢倒入要灌封的器件内。冬季施工作业，如果环境温度低于 5℃最好将 A、B 组分都预热至 15℃左右。
- 4、灌封好的工件于室温下固化，表干后方可进入下道工序，完全固化需要 1 天。夏季温度高，固化会快一些；冬季温度低，固化会慢一些。

注意事项

- 1、A 组分长时间放置若有沉淀或分层，应搅拌均匀后使用；B 组分低温下容易结晶，应提前放置温度较高室内使其溶化，不影响产品性能。
- 2、混合好的胶应一次用完，未用完的 A、B 两组份分别密封保存。
- 3、密封贮存于阴凉干燥处，贮存期六个月。

981 polyurethane encapsulant

It is used for potting various electronic components such as precision capacitors. It has high hardness after curing, and is a good material to replace epoxy resin. Vacuum degassing and heating equipment is required.

982 polyurethane encapsulant

It is used for potting and bonding of precision lightning arresters, various transformers, transformers, filters, control boards, igniters, etc.

983 polyurethane encapsulant

General-purpose type, suitable for potting all kinds of electronic products.

984 polyurethane encapsulant

It has excellent elasticity and toughness, can be repaired, has excellent electrical properties, and can replace silicone potting compound.

985 Polyurethane Adhesive:

Semi-flowing, used for bonding and sealing electronic components.

Attributes and Application

Two-component, room temperature curing, hardness adjustable polyurethane material, good fluidity, room temperature curing, cured into elastic rubber. It has excellent high and low temperature resistance, hydrolysis stability and excellent insulation properties. The potted electrical parts have a variety of functions such as fixing, insulation, heat dissipation, explosion-proof, and confidentiality. It is suitable for all kinds of pouring bonding and sealing of electronic components such as high-pressure, high-frequency, damp-hot environments and underwater instruments and meters.

Processing

1. Clean up the potting place, no oil, no water, no debris.
2. Weigh the A and B components according to the ratio, put them in the mixing tank, stir fully and mix evenly (do not stir the air into the glue when stirring). It is best to vacuum and degasser for about 5 minutes, and the amount of glue should not exceed 1/2 of the container, otherwise the glue will overflow during degassing.
3. Slowly pour the mixed rubber into the device to be potted. In winter construction work, if the ambient temperature is lower than 5 °C, it is best to preheat the A and B components to about 15 °C.
4. The potted workpiece is cured at room temperature, and the surface can only enter the next process after drying, and it takes 1 day to completely cure. In summer, the temperature is high, and the curing will be faster; In winter, when the temperature is low, the curing will be slower.

Notes:

1. If component A is placed for a long time and there is precipitation or stratification, it should be stirred evenly before use; Component B is easy to crystallize at low temperature, and should be placed in a higher temperature room in advance to dissolve without affecting the performance of the product.
2. The mixed glue should be used up at one time, and the unused A and B components should be sealed and stored separately.
3. Sealed and stored in a cool and dry place for six months.